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33168-2130IN THE CLAIMS:Claim 1 (currently amended)

1. A method of packaging a PVA sponge for use in scrubbing semiconductor wafers, said method comprising:

(a) placing said sponge in a [container] flexible plastic bag;

(b) said sponge containing a quantity of de-ionized water with around 0.05% to substantially less than 1% by volume of hydrogen peroxide; and

(c) sealing said [container] bag.

Claim 2 (withdrawn)Claim 3 (previously amended)

3. A method as in Claim 1 in which said quantity of de-ionized water with hydrogen peroxide is between an amount sufficient to wet said sponge and an amount necessary to saturate said sponge.

Claim 4 (previously amended)

4. A method as in Claim 1 in which the volume of hydrogen peroxide is around 0.1%.

Claim 5 (currently amended)

A method of packaging a [cleaning article] PVA sponge brush, said method comprising placing said cleaning article in a [container] plastic bag, said [cleaning article] sponge brush

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containing a quantity of de-ionized water, said water containing hydrogen peroxide in an amount effective to kill and retard the growth of bacteria in said cleaning article but less than an amount sufficient to develop significant quantities of metallic ions in said container, and sealing said container, in which said amount of hydrogen peroxide is about 0.05% to substantially less than 1% by volume.

Claim 6 (withdrawn)

Claim 7 (withdrawn)

Claim 8 (withdrawn)

Claim 9 (currently amended)

A packaged [cleaning article] PVA sponge for use in clean rooms, said cleaning article having particulate, metal ion and anionic counts at or below the values specified for a clean room, said package comprising a sealed [container] flexible plastic bag, said [cleaning article] sponge being positioned in said [container] bag, and containing a quantity of de-ionized water, said de-ionized water containing hydrogen peroxide in a concentration effective to kill and retard the growth of bacteria in said [cleaning article] sponge, said amount being low enough to substantially ensure decomposition of said hydrogen peroxide in a relatively short period of time after the

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container is sealed and being between 0.05% and substantially
less than 1% by volume.

Claim 10 (withdrawn)

Claim 11 (withdrawn)

Claim 12 (previously amended)

B 12. A cleaning article as in Claim 9 in which said
cleaning article is a PVA sponge for scrubbing semiconductor
wafer surfaces, and said concentration of hydrogen peroxide is
around 0.1 percent by volume.

Claim 13 (withdrawn)

Claim 14 (withdrawn)